Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!

Contact us

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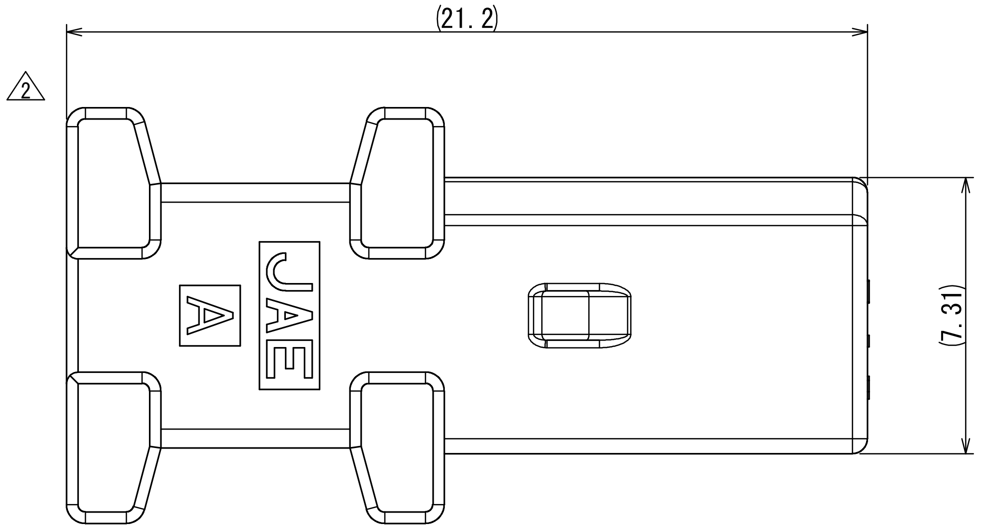
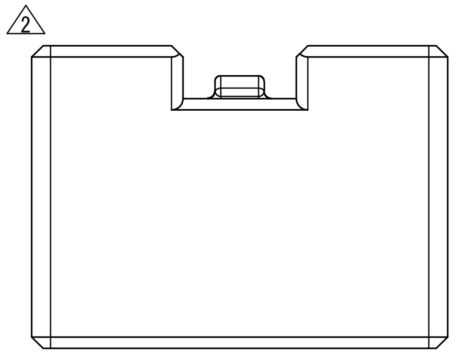
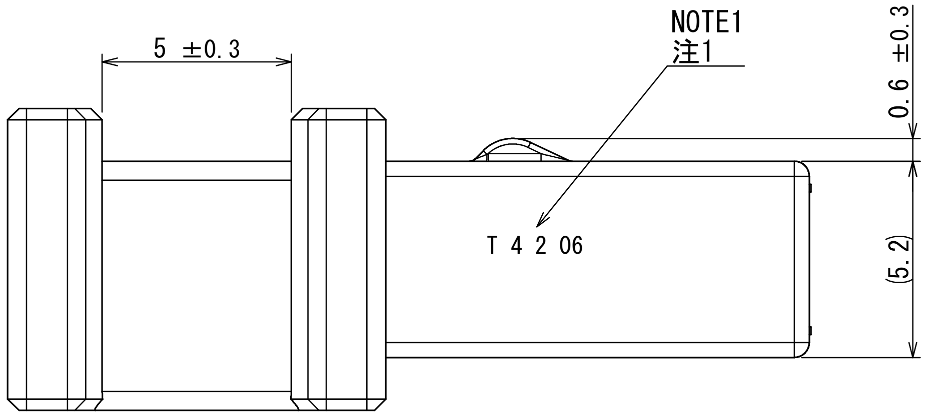
図面番号(DRAWING NO.)
SJ114930

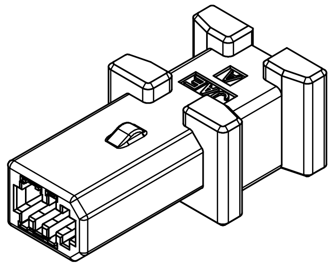
版数 VER.	年月日 DATE	CN NO.	変更内容 DESCRIPTION	製図 DR.	担当 CHK.	査閲 APPD.	承認 APPD.
2	25/JUL/2014	009573	DRAWING FORMAT ADD SPECIFICATION AND REVISED FORM	—	M.TANAKA	O.TAKAGI	T.MIYASHITA
3	03/OCT/2014	010509	REVISED PART LIST	—	M.TANAKA	O.TAKAGI	T.MIYASHITA

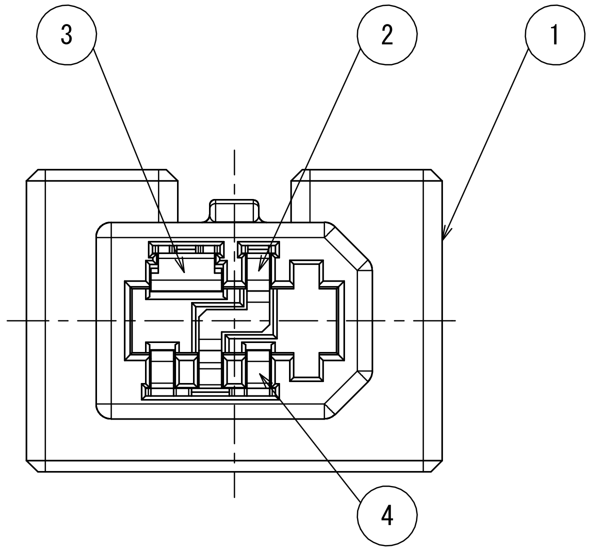
WISDOM承認 2014/10/06

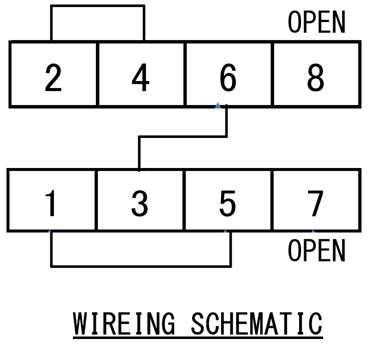












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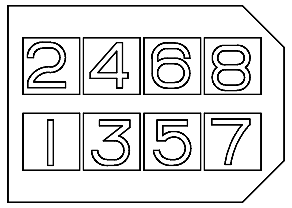

PIN NO.

NOTE1. PRODUCTION LOT NUMBER IS SHOWN AS INDICADED.

注記1.図示の位置にロットNo.を表示する。

Lot NO.(Ex.)
ロット NO.(例.)
T 4 2 06
Manufacture day.
製造日
Manufacture month.(JAN. TO SEP.:1~9,OCT.: 0,NOV.: X,DEC.:Y)
製造月(1月~9月:1~9,10月:0,11月:X,12月:Y)
Manufacture year.(It is shown at A.D. 1 digit.)
製造年(西暦の下1桁で表示する。)
Identification code(T:JAE Taiwan,Ltd)
組立部門識別(T:JAE Taiwan,Ltd)

3

符号 NO.	名称 DESCRIPTION	個数 QTY.	材料 MATERIAL	仕上 FINISH	備考 REMARKS
4	CONTACT3	1	COPPER ALLOY	SELECTIVE GOLD PLATING OVER NICKEL CONTACT AREA:GOLD 0.3μm MIN	—
3	CONTACT2	1	COPPER ALLOY	SELECTIVE GOLD PLATING OVER NICKEL CONTACT AREA:GOLD 0.3μm MIN	—
2	CONTACT1	1	COPPER ALLOY	SELECTIVE GOLD PLATING OVER NICKEL CONTACT AREA:GOLD 0.3μm MIN	—
1	INSULATOR	1	GLASS FILLED PLASTIC	—	—

仕様書(SPECIFICATION): JACS-30337 2
第1版(ORIGINAL DATE): 06/FEB/2014
尺度(SCALE): 5:1
シリーズ(SERIES): DZ02
製図 DR.: —
担当 CHK.: M.TANAKA
査閲 APPD.: O.TAKAGI
承認 APPD.: T.MIYASHITA
名称(TITLE): DZ02B008DC1
質量(MASS)

一般公差(GENERAL TOLERANCE)

寸法(DIMENSION)		角度(ANGLES)	
.	±0.8	×°	±
.×	±0.4	×°×'	±
.××	±0.1		
.×××	±		

単位(UNIT): mm

日本航空電子工業株式会社
JAPAN AVIATION ELECTRONICS INDUSTRY, LTD.

SIZE A3

図面番号(DRAWING NO.): SJ114930
版数(VER.): 3

S/W